



EVG Technology Day

in GRENoble, France
June 03, 2019 & June 04, 2019

Schedule

Monday, June 03, 2019

19:00 - 22:00 hrs

Dinner @ Les Saisons

Tuesday, June 04, 2019

08:30 - 16:00 hrs

EVG Technology Day

Location

Hotel Mercure

Grenoble Alpha Meylan

34, Avenue de Verdun
38240 Meylan, Grenoble, FRANCE

Guest Speaker



In cooperation with



Register

For more information
and to register for free:

www.EVGroup.com/events

Agenda

08:30	Registration
09:00	Welcome and Introduction Dr. Josef Meiler, Regional Sales Director Europe, EV Group (EVG)
09:10	Company Introduction Otto Bobenstetter, Regional Sales Manager Europe, EV Group (EVG)
09:20	Equipment Manufacturing Trends for More than Moore Devices Amandine Pizzagalli, Technology & Market Analyst - Semiconductor Manufacturing, Yole Développement
10:00	NIL - Technology Overview Dr. Martin Eibelhuber, Deputy Business Development, EV Group (EVG)
10:35	Coffee Break
10:50	NIL - Applications Dr. Martin Eibelhuber, Deputy Business Development, EV Group (EVG)
11:15	Advances in Resist and Adhesive Processing Dr. Thomas Uhrmann, Business Development Director, EV Group (EVG) Dr. Martin Eibelhuber, Deputy Business Development, EV Group (EVG)
12:15	Lunch
13:30	Update in Permanent Wafer Bonding by UV Wafer Bonding and High Vacuum Encapsulation Dr. Thomas Uhrmann, Business Development Director, EV Group (EVG)
14:15	Covalent Direct Bonding: From Mechanism to Applications Dr. Frank Fournel, Head of Bonding Engineering, CEA Leti
14:45	Coffee Break
15:15	Bonding Technology for 3D Integration: Temporary Bonding and High Accuracy Fusion Bonding Dr. Thomas Uhrmann, Business Development Director, EV Group (EVG)
16:00	Wrap-Up & Closing Remarks

